TDFS8C-3675X-10A

Rev. A

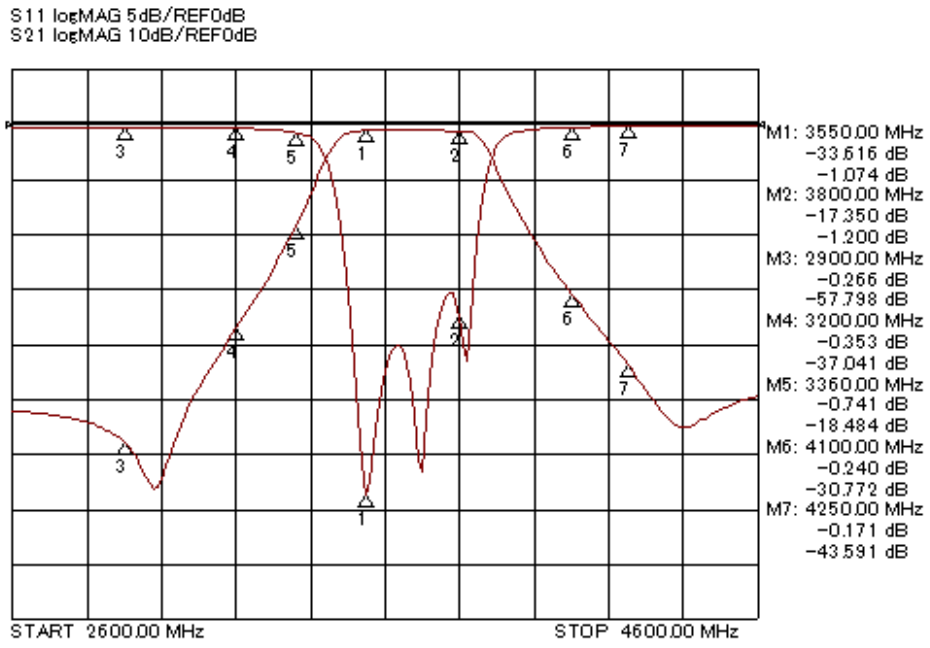
Part Number/Tape & Reel information

Part Number	Packaging	MOQ
TDFS8C-3675X-10AP	330 mm dia. reel	2000 pcs/reel

Specifications -40 to +85°C

Parameter	IN to OUT
Center Frequency	F0 : 3675 MHz
Band Width (BW)	F0 +/- 125 MHz
Insertion Loss	1.8 dB max.
Ripple at BW	1.0 dB max.
V.S.W.R. at BW	1.67 max.
Input Power	1.0 W max.
Attenuation	2900MHz 50dB min. 3200MHz 34dB min. 3360MHz 16dB min. 4100MHz 25dB min. 4250MHz 37dB min.
Characteristic Impedance	50 Ohms

Frequency Response



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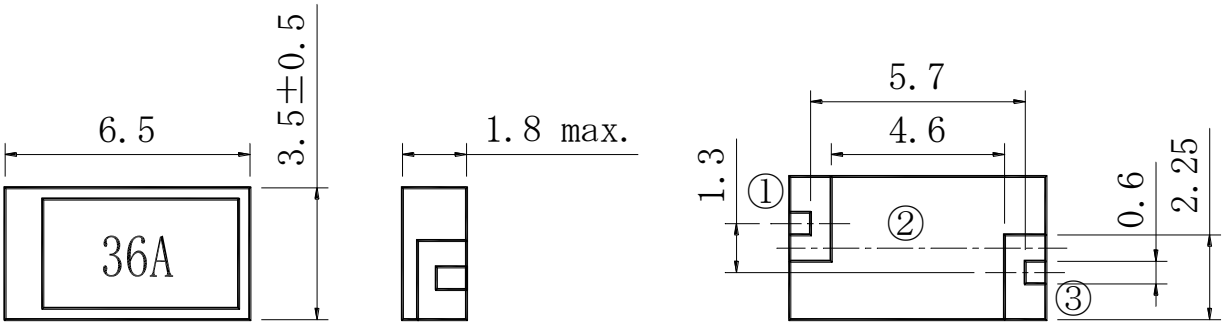
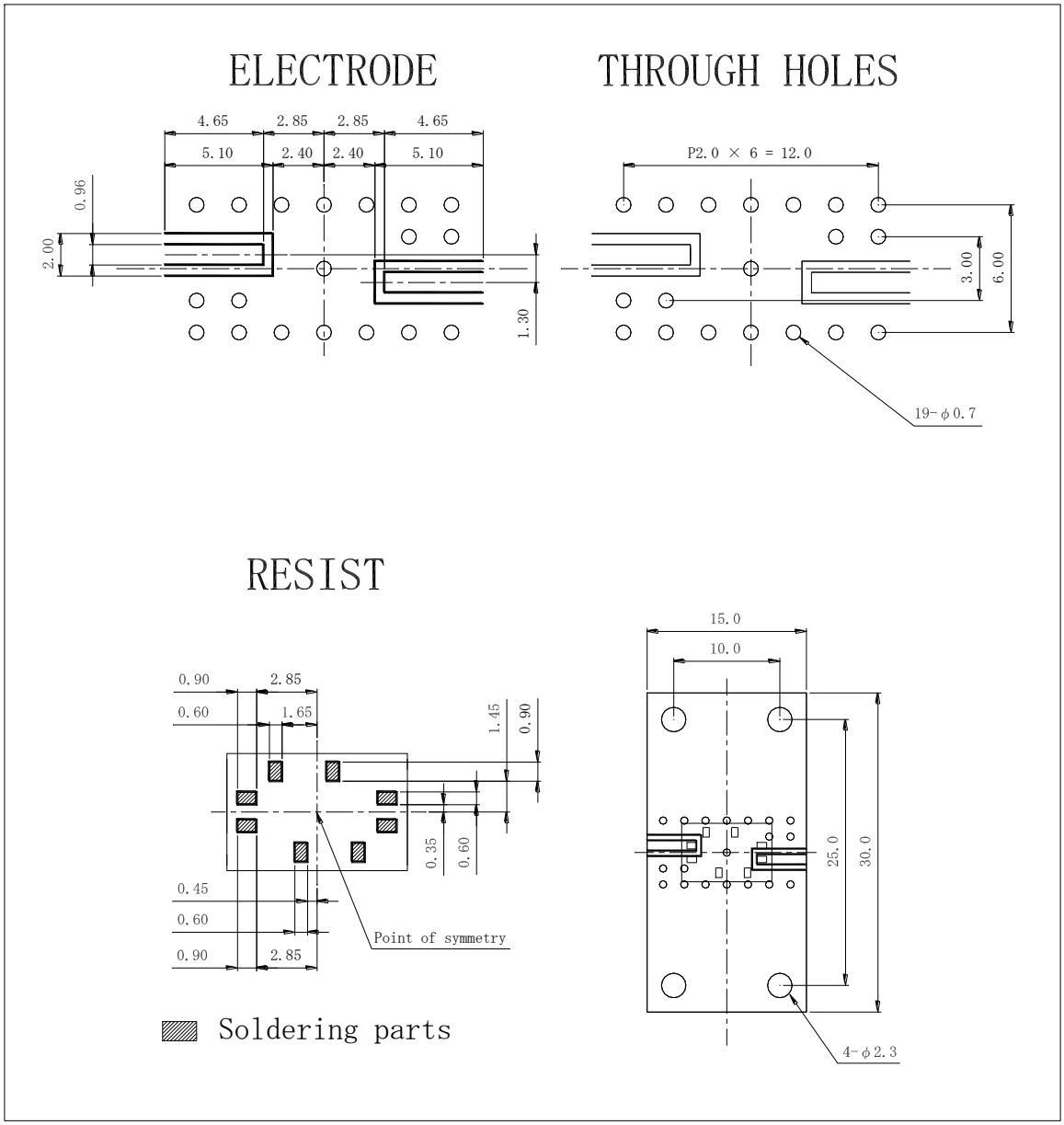
Dimensions and Marking



Tolerance:±0.3
Unit:mm

①	Out	③	In
②	GND		

Recommend Land Pattern (reference)



Note : Impedance of signal lines should be 50 ohms including land pattern. This standard condition is applying to the BT resin board (t = 0.4, dielectric constant = 3.6, copper plating on both surfaces).

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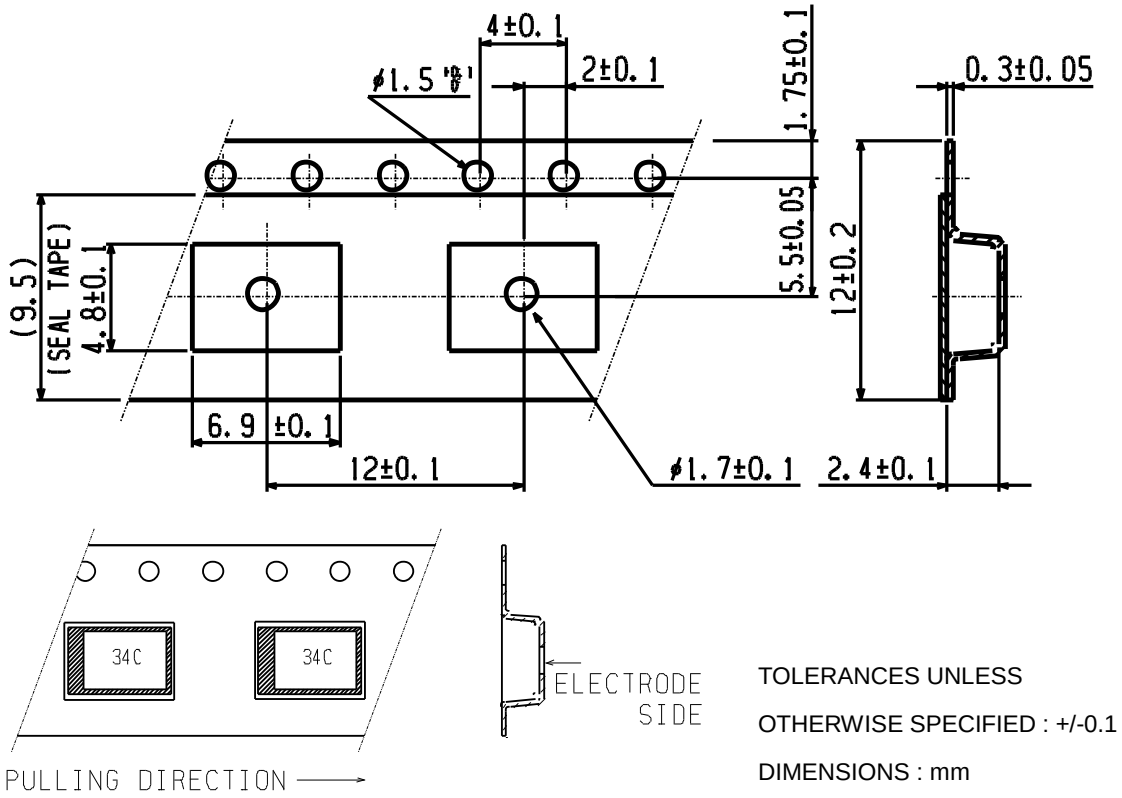
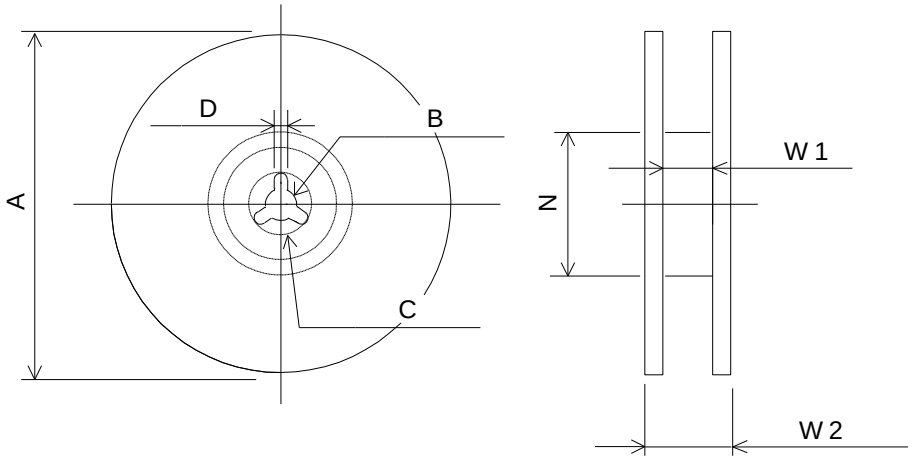
Dimensions of Carrier Tape



TOLERANCES UNLESS OTHERWISE SPECIFIED : +/-0.1

DIMENSIONS : mm

Dimensions of Reel



Murata Part Number	A+/-2.0	B+/-0.5	C+/-1.0	D+/-0.5	N (min.)	W1+/-0.5	W2+/-1.0
TDFS8C-3675X-10AP	φ 330	φ 13	φ 21	2	φ 80	13.5	17.5

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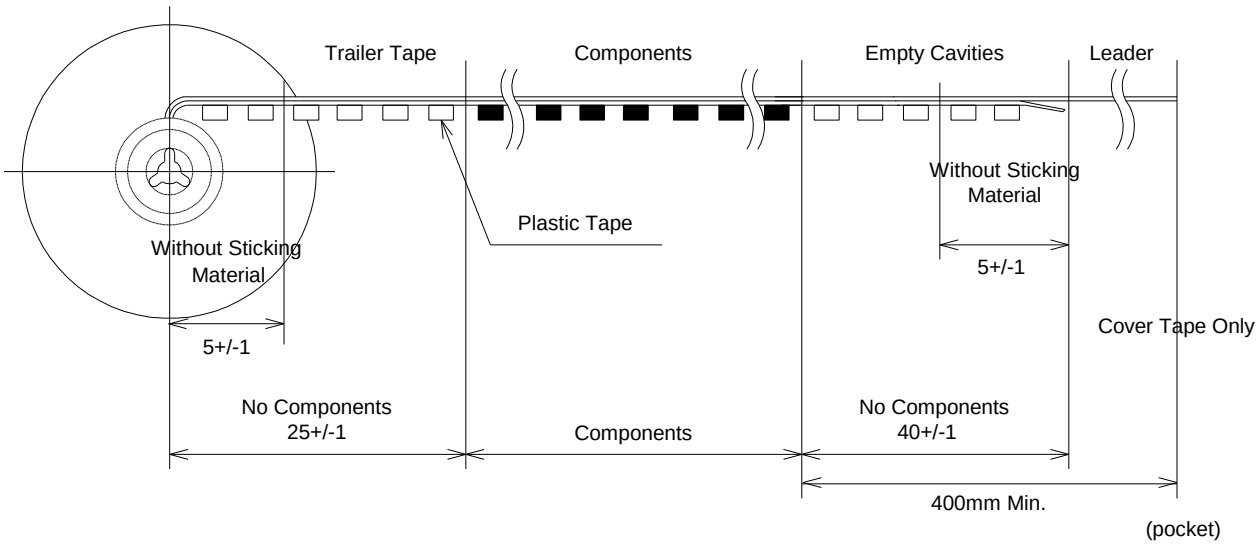
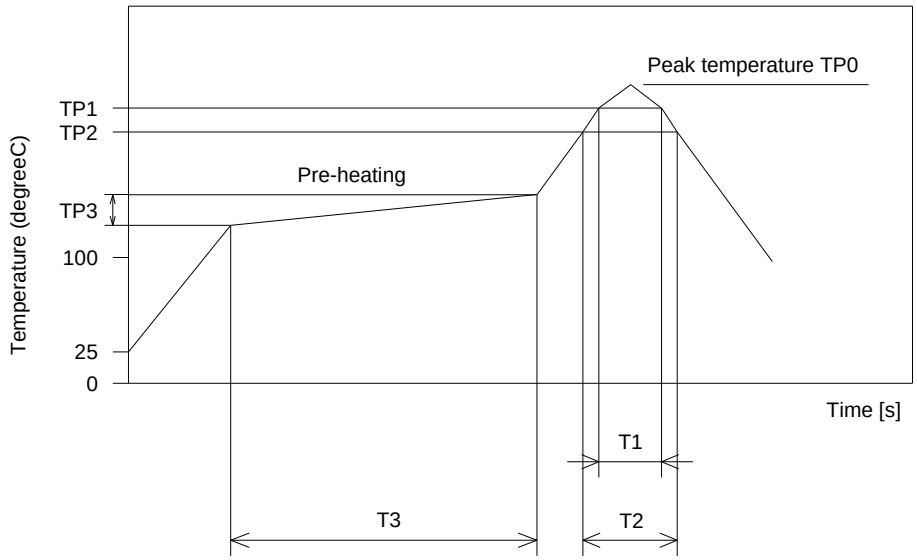
Taping Condition



Reflow Soldering Standard Conditions



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

		TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)	T3 (s)
Reflow standard condition	Sn-40Pb solder	235+/-5	230	10 max.	200	45 to 55	70 to 130	70 to 130
	Sn-3Ag-0.5Cu solder	255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120
Test condition of reflow heat resistance		255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120

Reflow soldering is available 2 times for above test condition of reflow heat resistance.